



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20352Generic Copy

Issue Date: 24-Jan-2014**TITLE:** Material Change on Leadframe and Mold resin of SOIC8L as to DC-DC Converter LV58063MC.**PROPOSED FIRST SHIP DATE:** 02-Jun-2014**AFFECTED CHANGE CATEGORY(S):** Material of Leadframe and Mold resin**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or
<Hiroyuki.Hirano@onsemi.com> <Kazuhiko.Saitoh@onsemi.com>**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCEN)

First change notification sent to customers. IPCENs are issued at least 120 days prior to implementation of the change. An IPCEN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCEN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

The purpose of this change is to increase the units in the Leadframe for enhancement of the manufacturing process with greater efficiency & productivity. The Mold resin is changed at the same time.

The package outline dimension has no change. And the characteristic and quality also will have no impact.

In addition, there are no changes such as the mark on the package. This change can be traced by package marking lot number.



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QUALIFICATION PLAN:

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Test Items		Test Conditions	Test Time
Temperature Humidity Bias	*	Ta=85°C, RH=85%, Vcc(VDD)= Vccmax	1000hrs
Temperature Cycle	*	Ta=-65°C 30min. to Ta=150°C 30min.	100cycles
Pressure Cooker	*	Ta=121°C,RH=100% , 205KPa	100hrs
High Temperature Storage		Ta=150°C	1000hrs

Notice) The test items with * mark are put into operation after the reflow soldering. (MSL3 Preconditioning, 3 IR @ 260 °C)

List of affected General Parts:

LV58063MC-AH